Semiconductor Monitoring Burn-in Test Chamber ETSP- BTC series

Product Intro

ETSP-BTC series are Semiconductor Monitoring Burn-In test chambers to stress semiconductor packaged device s to ensure optimum performance as well as to weed o ut defective semiconductor packaged devices which can cause reliability problems in the end product.

General Features

- Uniform high accurate and reliable temperature control
- Easy of operation and simplicity
- Friendly, flexible, up-to date control and management systems
- Allows easy servicing and upgrades
- Selectable between manual door type (BTC 1000) and automatic door type (BTC 2000)
- Computer control is available
- Network connection of several chambers to a single "master" control unit allowing centralized supervision both in local and remote mode

Technical Features

Temperature range	40 ℃ ~ 150 ℃ (changeable according to user's demand)
Temperature uniformity	Less than ± 0.5 ℃
Temperature rising time	RT to 125 ℃ less than 50 minutes
Temperature cooling time	125 ℃ to RT less than 50 minutes
Cool own rate	More than 1~5 ℃/min
Input power requirements	230V ±10%, 380V ±10%, 50Hz/60Hz, 1Ph/3Ph

Technical Specifications

Model	Internal dimensions	External dimensions	Note
ETSP-BTC 1000	1250x650x1300 (WxDxH) mm	2250x1500x2500 (WxDxH) mm	Manual door
ETSP-BTC 2000	1250x1500x2500 (WxDxH) mm	1250x650x1300 (WxDxH) mm	Automatic door

- Controller : Touch screen LCD programmable type (6,000step, 300 profile)
- No. of zones : 1
- No. of slots for BIB (Burn in Board) : 48 (In case of BIB size is 450x571x1.6t (WxD mm))
- Refrigeration : cooling system for refrigeration or fresh air or cooled water
- Inside material : STS304, 1.2t, polishing
- Exterior material : CR 2.0t, painting
- Safety devices : Switch-off after alarm for Overheating, Current leak, Over current, Door open (ELB, BKM, OHP, E-Stop Switch, Tower lamp)

Options

- Chart recorder
- T/C (Thermal couple) data acquisition (8, 16, 24, 32 Ch)
- Chamber networking connection system (RS422/RS485)
- Customization available